

### SCMM2512S2 Series, Current Sensor Resistor (Lead / Halogen Free)

### Features / Applications :

- High power rating is up to 2W
- Welding construction; excellent long-term stability
- Automotive applications & Current Sensor Resistor
- Suggested mounting on DBC/IMS/FR4 substrate
- RoHS compliant

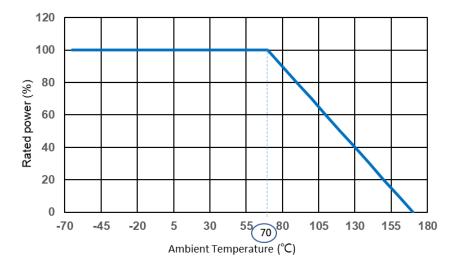


### **Electrical Specifications :**

Characteristics <sup>1</sup>	Feature
Power Rating <sup>2</sup>	2 W
Resistance Value	15 m $\Omega$
Temperature Coefficient of Resistance (25/125 $^\circ$ C)	From 50 ppm/°C
Operation Temperature Range	-65°C~ +170°C
Resistance Tolerance	$\pm$ 1%
Maximum Working Voltage (V)	(P*R) <sup>1/2</sup>

1. For detail information refer to the table on page 3 P/N list

2. For resistors are operated at ambient temperature in excess of 70°C, the maximum load shall be derated in accordance with the following curve.

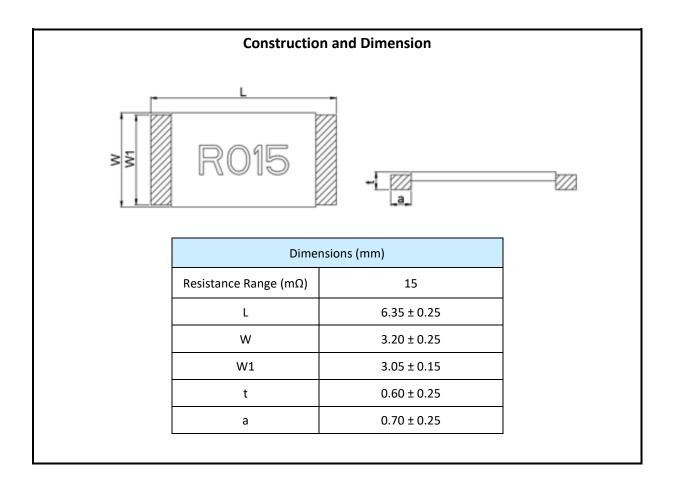




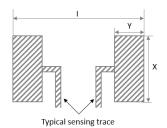
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### Outline Drawing :



#### Recommended Solder Pad Dimensions



Resistance Range	Dimensions				
mΩ	X (mm) Y (mm) I (mm)				
15	3.7	1.65	7.35		



SCMM	2512	S		_		
(1)	(2)	(3)	(4)		(5)	(6)

Note :

- (1) Series No.
- (2) Size
- (3) Terminal Type : S = Short terminal
- (4) Power Rating : 2 = 2W
- (5) Resistance value : R015 =  $0.015\Omega$
- (6) Tolerance :  $F = \pm 1\%$ ,  $G = \pm 2\%$ ,  $J = \pm 5\%$

### P/N list :

P/N	R value	TCR	Power Rating		Tolerance	
P/N	(mΩ)	(ppm/K)	(W)	1%	2%	5%
SCMM2512S2-R015*	15.0	±50	2	✓		

\* Note : Other values and tolerance would be available, please contact Cyntec.



### Electrical

ltem	Specification and Requirement	Test Method
Temperature Coefficient (TCR)	As follow specification	JIS-C-5201 +25°C / +125°C.
Short Time Overload	$\triangle R: \pm 0.5\%$ Without damage by flashover, spark, arcing, burning or breakdown	JIS-C-5201-1 4.13 2.5 x rated power for 5 seconds.
ESD	$\triangle R: \pm 1\%$ Without damage by flashover, spark, arcing, burning or breakdown	AEC-Q200-002 Human body, 8KV.
Insulation Resistance	Over 100 M $\Omega$ on Overcoat layer face up	JIS-C-5201-1 4.6 100V <sub>DC</sub> for 60 +10/-0 seconds
Voltage Proof	$ riangle { m R}:\pm$ 1% Without damage by flashover, spark, arcing, burning or breakdown	JIS-C-5201-1 4.7 400V <sub>AC</sub> (rms.) for 60 +10/ -0 seconds

#### Mechanical

Item	Specification and Requirement	Test Method
Solderability	The surface of terminal immersed shall be minimum of 95% covered with a new coating of solder	J-STD-002 Method B category 3 245±5°C for 5±0.5 seconds.
Resistance to Solder	$\triangle R: \pm 0.5\%$	MIL-STD-202 Method 210
Heat	Without distinct damage in appearance	260 $\pm$ 5°C for 10 $\pm$ 1 seconds.
Board Flex	$ riangle R:\pm$ 1.0% Without mechanical damage such as break.	AEC-Q200-005 Bending value: 2 mm for 60 ± 1 seconds.
Vibration	$ riangle R:\pm 0.5\%$ Without distinct damage in appearance	MIL-STD-202 Method 204 5G's for 20 minutes, 12 cycles each of 3 orientations. Test from 10- 2000Hz.

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Mechanical Shock	$ riangle R:\pm$ 0.5% Without distinct damage in appearance	MIL-STD-202 Method 213 100G's peak value, 6ms, Half-sine waveform, 12.3ft/sec.
Terminal Strength	$ riangle { m R}:\pm$ 1%	AEC-Q200-006
(SMD)	Without mechanical damage such as break.	Force of 1.8Kg for 60 seconds.

### Endurance

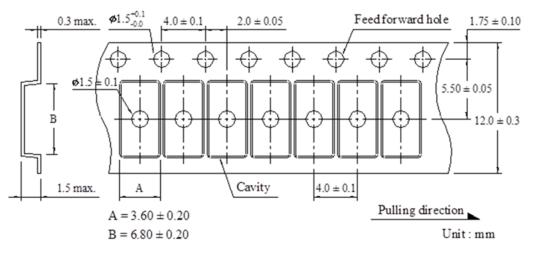
Item	Specification and Requirement	Test Method
Temperature Cycling	$ riangle R:\pm$ 0.5% Without distinct damage in appearance	JESD22 Method JA-104 -55°C to 150°C /1000cycle 30 min maximum dwell time at each temperature on FR4(PCB).
Biased Humidity	$ riangle { m R}:\pm$ 0.5% Without distinct damage in appearance	MIL-STD-202 Method 103 1000 hours, 85°C /85%R.H, applied for 10% rated power.
Operational Life	$ riangle R:\pm$ 1.0% Without distinct damage in appearance	MIL-STD-202 Method 108 70°C, 100% rated power 1.5 hours ON, 0.5 hours Off For total 1000 hours
High Temperature Storage	$ riangle { m R}:\pm$ 1.0% Without distinct damage in appearance	MIL-STD-202 Method 108 170°C for 1000 hours.
Moisture Resistance	$ riangle { m R}:\pm$ 0.5% Without distinct damage in appearance	MIL-STD-202 Method 106 65°C /90-100%RH, unpowered, 7b not required

Note : Measurement at 24 $\pm$ 4 hours after test conclusion for all reliability tests-parts.

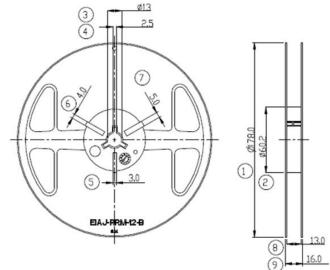


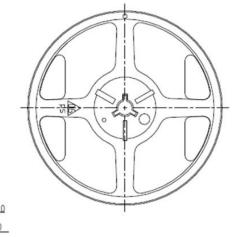
### **PACKAGING DESCRIPTIONS :**

### Dimensions :



Reel dimensions :





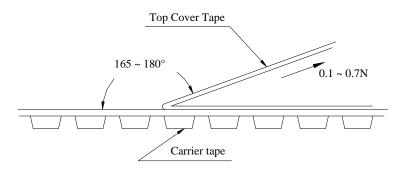
Unit :mm

Symbol	1	2	3	4	5	6	7	8	9
Sizo	178.0	60.2	13.0	2.5	3.0	4.0	5.0	13.0	16.0
Size	±1	±0.5	±0.5	+0.5/-0	+0.5/-0	+0.5/-0	+0.5/-0	±0.5	±0.15



### Peel Strength of Top Cover Tape :

The peel speed shall be about 300mm/min and the peel force of top cover tape shall between 0.1 to 0.7N



### Number of Taping :

2,000 pieces / reel

#### Label Marking :

The following items shall be marked on tray

- (1) Description
- (2) Quantity
- (3) Part No.
- (4) Tapping No.



### Care Note :

#### Care note for storage

(1) Chip resistor shall be stored in a room where temperature and humidity must be controlled.

(temperature 5 to 35°C, humidity < 60% RH) However, a humidity keep it low, as it is possible.

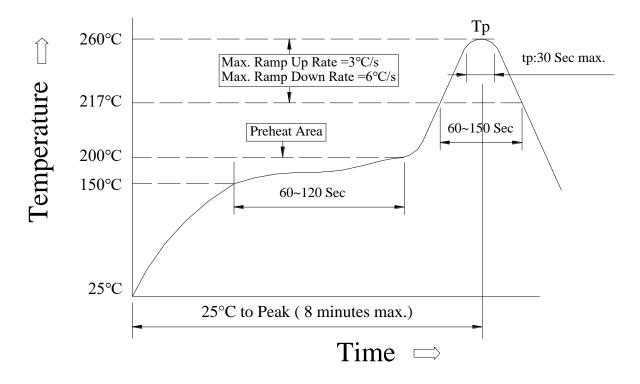
- (3) Chip resistor shall be stored as direct sunshine doesn't hit on it.
- (4) Chip resistor shall be stored with no moisture, dust, a material that will make solderability inferior, and a harmful gas (Chloridation hydrogen, sulfurous acid gas, and sulfuration hydrogen)

#### Care note for operating and handling

- (1) Protect the edge and coating of the sensors from mechanical stress.
- (2) Avoid bending of printing circuit board (PCB) when cutting and fixing it on support body to reduce mechanical stress on sensors.
- (3) Sensor should be used within the condition of specification.
   Note: When a voltage higher than specified value is loaded to the sensor, this may damage the sensor material due to temperature rise.
- (4) The loaded voltage should consult terminal temperature of the sensor according to the derating curve.
- (5) When applying a high current exceeding suggested specification (pulse current, shock current) to the sensor, it is necessary to re-evaluate the operating condition before using it in the system.



**Recommended Reflow Profile** 



(1) Reflow Soldering Method :

Reflow Soldering	Tp:255~260°C	Max.30 seconds ( tp )
	217°C	60~150 seconds
Pre-Heat	150 ~ 200°C	60~120 seconds
Time 25°C to peak temperature	8 minutes max.	

Reference : JEDEC J-STD-020E